



SOT607-1

plastic thin shrink small outline package; 30 leads; body width 4.4 mm; lead pitch 0.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP30
Package type industry code	TSSOP30
Package style descriptive code	TSSOP (thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	18-2-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		7.7	-	7.8	7.9	mm
E	package width		4.3	-	4.4	4.5	mm
A	seated height		[tbd]	-	1.1	1.1	mm
A ₂	package height		0.85	-	0.9	0.95	mm
n ₂	actual quantity of termination		-	-	30	-	



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2. Package outline

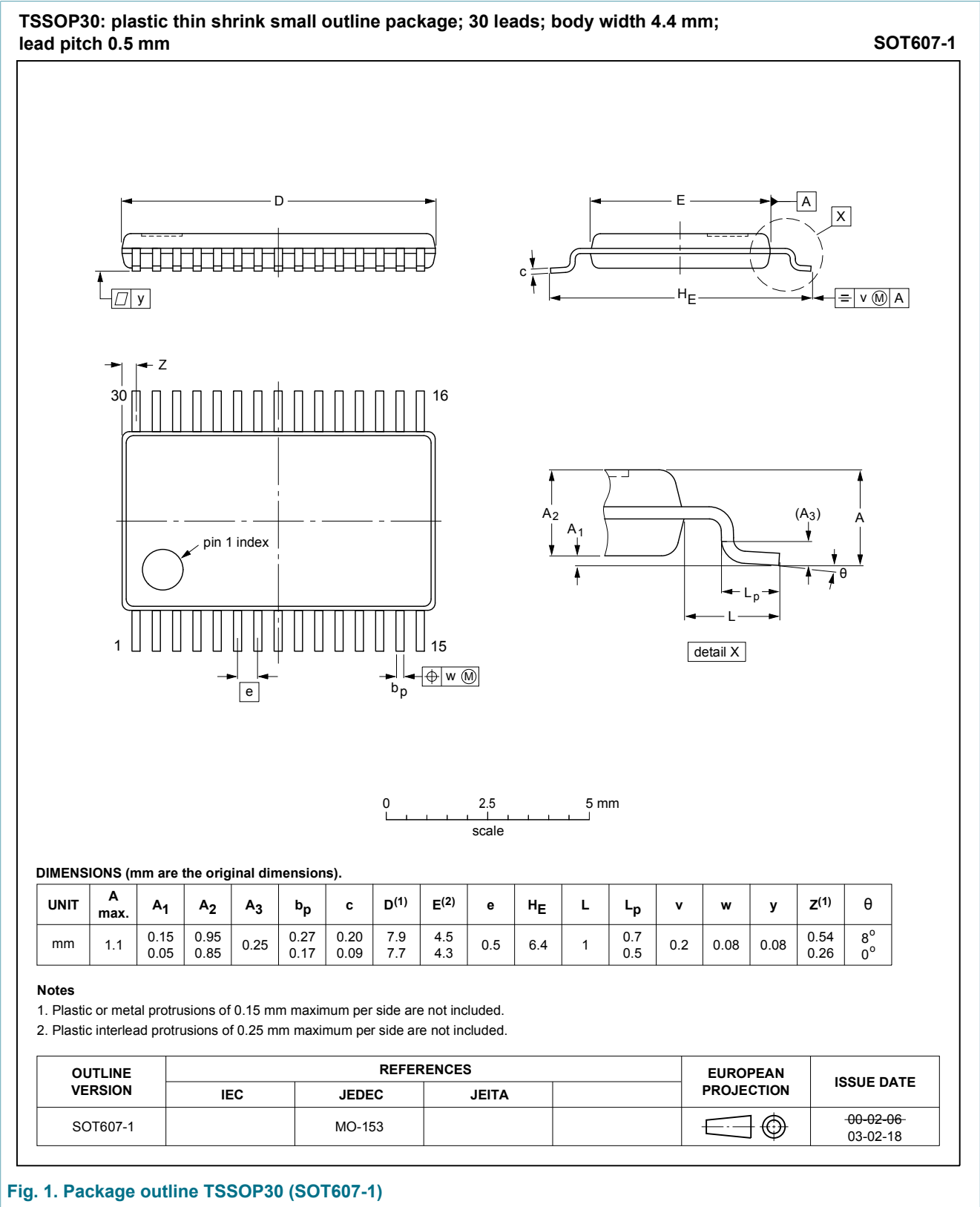


Fig. 1. Package outline TSSOP30 (SOT607-1)

plastic thin shrink small outline package; 30
leads; body width 4.4 mm; lead pitch 0.5 mm

3. Soldering

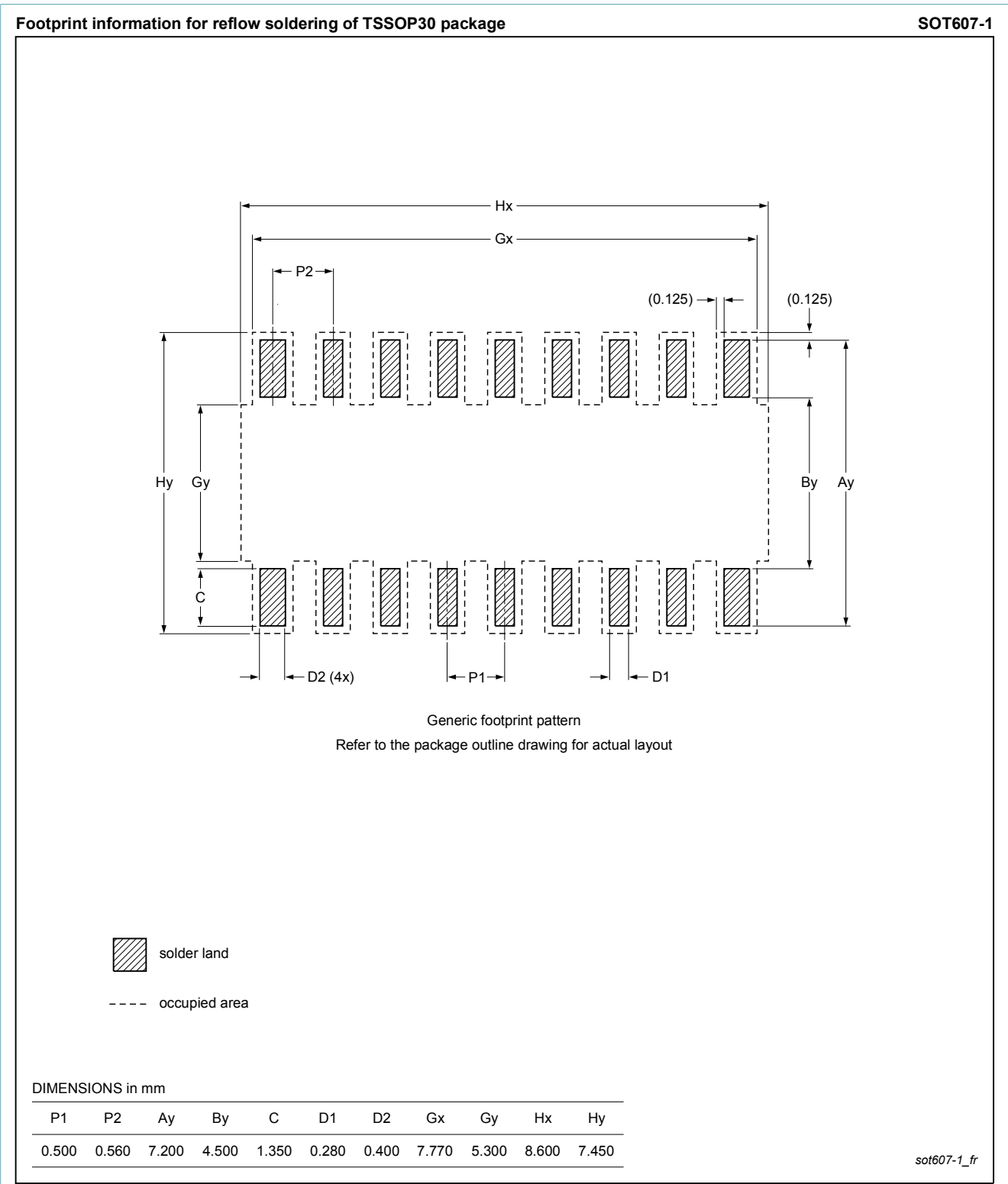


Fig. 2. Reflow soldering footprint for TSSOP30 (SOT607-1)

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4. Legal information

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